

6. (Twice Amended) The method according to claim 3, wherein
the portion (8) is planar.

8. (Twice Amended) The method according to claim 6, wherein
the portion (8) is one of circular, oval and polygonal in cross-section when viewed
from above.

10. (Twice Amended) A method for applying a thin-walled, flat
substrate to an assembly carrier (6) with a protective layer (5), the improvement
comprising:

with respect to the protective layer (5), arranging the substrate at a
spacing and curved in a convex manner, contacting the protective layer (5) with the
substrate (4), and laying the substrate (4) over the protective layer (5) from a contact
point towards an edge of the substrate, and the substrate being arched and detached
from a carrying body (2) by controlling a pressure of a medium in a cavity between
the substrate (4) and the carrying body (2);

the carrying body (2) moveable relative to the assembly carrier (6) and
including a portion (8) facing the protective layer (5) and carrying the substrate (4),
the portion (8) having a plurality of flow apertures (3, 7) for accommodating the

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pressure medium, the flow apertures (3, 7) including at least one centrally formed duct (7) configured as an overpressure line and circumferential grooves (3) configured as negative pressure lines.

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12. (Twice Amended) The method according to claim 10, wherein the portion (8) is one of circular, oval and polygonal in cross-section when viewed from above.

Please add the following new claims.

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13. (New) An apparatus for applying a thin-walled, flat

substrate (4) to an assembly carrier (6) with a protective layer (5), the improvement comprising:

with respect to the protective layer (5), a means for arranging the substrate (4) at a spacing and curved in a convex manner for contacting the protective layer (5) and for laying the substrate (4) over the protective layer (5) from a contact point towards an edge of the substrate, wherein the substrate (4) is arched and detached from a carrying body (2) by controlling a pressure of a medium in a cavity between the substrate (4) and the carrying body (2); and

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the carrying body (2) moveable relative to the assembly carrier (6) and including a portion (8) facing the protective layer (5) and carrying the substrate (4), the portion (8) having a plurality of flow apertures (3, 7) for accommodating the pressure medium, the flow apertures (3, 7) including at least one centrally formed duct (7) configured as an overpressure line and circumferential grooves (3) configured as negative pressure lines.

14. (New) The apparatus according to claim 13, wherein when laid, the substrate (4) applies a constant pressure on the protective layer.

15. (New) The apparatus according to claim 14, wherein the pressure medium is applied to a side of the substrate (4) remote from the protective layer (5).

16. (New) The apparatus according to claim 13, wherein the portion (8) is planar.

17. (New) The apparatus according to claim 16, wherein the portion (8) is one of circular, oval and polygonal in cross-section when viewed from above.

18. (New) The apparatus according to claim 13 wherein the pressure medium is applied to a side of the substrate (4) remote from the protective layer (5).

19. (New) The apparatus according to claim 13, wherein the portion (8) is one of circular, oval and polygonal in cross-section when viewed from above.

20. (New) An apparatus for applying a thin-walled flat substrate (4) to an assembly carrier (6) with a protective layer (5), comprising:
a carrying body (2) moveable relative to the assembly carrier (6), the carrying body (2) including a portion (8) facing the protective layer (5);
the portion (8) including at least one centrally formed duct (7), wherein the centrally formed duct (7) is configured as an overpressure line;

the portion (8) including at least one circumferential groove (3) at a periphery, wherein the at least one circumferential groove (3) is configured as a negative pressure line;

wherein the negative pressure line is adapted to hold the substrate (4), the overpressure line is adapted to arch the substrate (4) outward from the portion (8), and the substrate is detachable from the carrying body (2) by controlling a pressure medium in a cavity between the substrate (4) and the portion (8).

21. (New) The apparatus according to claim 20, wherein the pressure medium is applied to a side of the substrate (4) remote from the protective layer (5).

22. (New) The apparatus according to claim 20, further comprising more than one circumferential groove (3).

23. (New) The apparatus according to claim 20, wherein the portion (8) is one of circular, oval and polygonal in cross-section when viewed from above.